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features

- Multi-Rate Operation from 155 Mbps Up to 2.5 Gbps
- Ultralow Power Consumption
- Input Offset Cancellation
- High Input Dynamic Range
- Output Disable
- Output Polarity Select
- CML Data Outputs

- Single 3.3-V Supply
- Surface Mount Small Footprint 3 mm × 3 mm 16-Pin QFN Package

applications

- SONET/SDH Transmission Systems at OC3, OC12, OC24, OC48
- 1.0625-Gbps and 2.125-Gbps Fibre Channel Receivers
- Gigabit Ethernet Receivers

description

The ONET2511PA is a versatile high-speed limiting amplifier for multiple fiber optic applications with data rates up to 2.5 Gbps.

This device provides a gain of about 50 dB, which ensures a fully differential output swing for input signals as low as 3 mV_{p-p} .

The high input signal dynamic range ensures low jitter output signals even when overdriven with input signal swings as high as 1200 mV_{p-p} .

The ONET2511PA is available in a small footprint 3 mm \times 3 mm 16-pin QFN package. The circuit requires a single 3.3-V supply.

This power efficient limiting amplifier is characterized for operation from -40°C to 85°C

available options

| TA | PACKAGED DEVICE | FEATURES | | |
|---------------|-----------------|--|--|--|
| -40°C to 85°C | ONET2511PARGT | 2.5-Gbps ultralow power limiting amplifier | | |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



block diagram

A simplified block diagram of the ONET2511PA is shown in Figure 1.

These compact, low power 2.5-Gbps limiting amplifier consists of a high-speed data path with offset cancellation block, a loss of signal and RSSI detection block, and a bandgap voltage reference and bias current generation block.

The limiting amplifier requires a single 3.3-V supply voltage. All circuit parts are described in detail below.

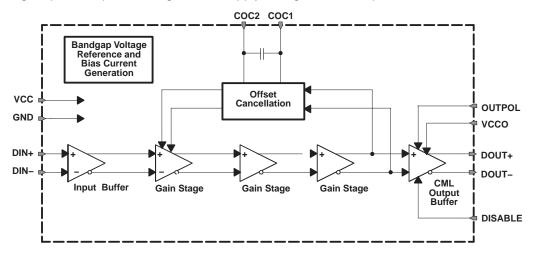


Figure 1. Block Diagram

high-speed data path

The high-speed data signal is applied to the data path by means of the input signal pins DIN+/DIN–. The data path consists of the input stage with 2×50 - Ω on-chip line termination to VCC, three gain stages which provide the required typical gain of about 50 dB, and a CML output stage. The amplified data output signal is available at the output pins DOUT+/DOUT–, which provide 2×50 - Ω back-termination to VCCO. The output stage also includes a data polarity switching function, which is controlled by the OUTPOL input and a disable function, controlled by the signal applied to the DISABLE input pin.

An offset cancellation compensates inevitable internal offset voltages and thus ensures proper operation even for small input data signals.

The low frequency cutoff is as low as 45 kHz with the built-in filter capacitor.

For applications, which require even lower cutoff frequencies, an additional external filter capacitor may be connected to the COC1/COC2 pins.

bandgap voltage and bias generation

The ONET2511PA limiting amplifier is supplied by a single 3.3-V \pm 10% supply voltage connected to the VCC and VCCO pins. This voltage is referred to ground (GND).

An on-chip bandgap voltage circuitry generates a supply voltage independent reference from which all other internally required voltages and bias currents are derived.



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package

For the ONET2511PA a small footprint 3 mm \times 3 mm 16-pin QFN package is used, with a lead pitch of 0,5 mm. The pinout is shown in Figure 2.

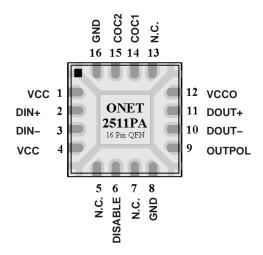


Figure 2. Pinout of ONET2511PA in a 3 mm \times 3 mm 16-Pin QFN Package

terminal functions

The following table shows a pin description for the ONET2511PA in a 3 mm x 3 mm 16-pin QFN package.

| TERMINAL | | TYPE | DESCRIPTION | | |
|----------|-----------|-----------|---|--|--|
| NAME | NO. | ITPE | DESCRIPTION | | |
| VCC | 1, 4 | Supply | 3.3-V ±10% supply voltage | | |
| DIN+ | 2 | Analog in | Noninverted data input. On-chip 50-Ω terminated to VCC | | |
| DIN- | 3 | Analog in | Inverted data input. On-chip 50- Ω terminated to VCC | | |
| N.C. | 5, 7, 13 | | Not connected | | |
| DISABLE | 6 | CMOS in | Disables CML output stage when set to high level | | |
| GND | 8, 16, EP | Supply | Circuit ground. Exposed die pad (EP) must be grounded. | | |
| OUTPOL | 9 | CMOS in | Output data signal polarity select (internally pulled up): Setting to high level or leaving pin open selects normal polarity. Low level selects inverted polarity. | | |
| DOUT- | 10 | CML out | Inverted data output. On-chip 50-Ω back-terminated to VCCO | | |
| DOUT+ | 11 | CML out | Noninverted data output. On-chip 50-Ω back-terminated to VCCO | | |
| VCCO | 12 | Supply | 3.3-V ±10% supply voltage for output stage | | |
| COC1 | 14 | Analog | Offset cancellation filter capacitor terminal 1. Connect an additional filter capacitor between this pin and COC2 (pin 15). To disable the offset cancellation loop connect COC1 and COC2 (pins 14 and 15). | | |
| COC2 | 15 | Analog | Offset cancellation filter capacitor terminal 2. Connect an additional filter capacitor between this pin and COC1 (pin 14). To disable the offset cancellation loop connect COC1 and COC2 (pins 14 and 15). | | |

absolute maximum ratings

over operating free-air temperature range unless otherwise noted[†]

| | | VALUE | UNIT |
|--|--|-----------|------|
| V _{CC} , V _{CCO} | Supply voltage, See Note 1 | -0.3 to 4 | V |
| V _{DIN+} , V _{DIN-} | Voltage at DIN+, DIN-, See Note 1 | 0.5 to 4 | V |
| VDISABLE, VOUTPOL, VDOUT+, VDOUT-, VCOC1, VCOC2+ | Voltage at TH, DISABLE, OUTPOL, DOUT+, DOUT-, COC1, and COC2, See Note 1 | -0.3 to 4 | V |
| VCOC_DIFF | Differential voltage between COC1 and COC2 | ±1 | V |
| VDIN_DIFF | Differential voltage between DIN+ and DIN- | ±2.5 | V |
| IDIN+, IDIN-, IDOUT+, IDOUT- | Continuous current at inputs and outputs | -25 to 25 | mA |
| T _{J(max)} | Maximum junction temperature | 125 | °C |
| T _{stg} | Storage temperature range | -65 to 85 | °C |
| TA | Characterized free-air operating temperature range | -40 to 85 | °C |
| TL | Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260 | °C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

recommended operating conditions

| | MIN | TYP | MAX | UNIT |
|--|-----|-----|-----|------|
| Supply voltage, V _{CC} , V _{CCO} | 3 | 3.3 | 3.6 | V |
| Operating free-air temperature, T _A | -40 | | 85 | °C |

dc electrical characteristics

over recommended operating conditions (unless otherwise noted)

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------------------|--|---|------|------|------|------------|
| Vcc,√cco | Supply voltage | | 3 | 3.3 | 3.6 | V |
| lvcc | Supply current | DISABLE = low (excludes CML output current) | | 22 | 28 | mA |
| | Differential data output voltage swing | DISABLE = high | | 0.25 | 10 | mV_{p-p} |
| VOD | | DISABLE = low | 600 | 780 | 1200 | mV_{p-p} |
| R _{IN} , R _{OUT} | Data input/output resistance | Single ended | | 50 | | Ω |
| V _{IN,MIN} | Data input sensitivity | BER < 10 ⁻¹⁰ | | 3 | 5 | mV_{p-p} |
| V _{IN,MAX} | Data input overload | | 1200 | | | mV_{p-p} |
| | CMOS input high voltage | | 2.1 | | | V |
| | CMOS input low voltage | | | | 0.6 | V |
| PSNR | Power supply noise rejection | f < 2 MHz | 26 | | | dB |

ac electrical characteristics

over recommended operating conditions (unless otherwise noted) typical operating condition is at V_{CC} = 3.3 V and T_A = 25°C

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|----------------|----------------------------------|--|-----|-----|-----|-------------------|--|
| | | C _{OC} = open | | 45 | 70 | kHz | |
| | Low frequency –3-dB bandwidth | C _{OC} = 2.2 nF | | 0.8 | | | |
| | Data rate | | 2.5 | | | Gb/s | |
| ٧NI | Input referred noise | | | | 300 | μV_{RMS} | |
| | Deterministic jitter, See Note 2 | K28.5 pattern at 2.5 Gbps | | 8.5 | 25 | ps _{p-p} | |
| DJ | | 2 ²³ –1 PRBS equivalent pattern at 2.5 Gbps | | 9.3 | 30 | | |
| | | 2 ²³ –1 PRBS equivalent pattern at 155 Mbps | | 25 | 50 | | |
| <u> </u> | Random jitter | Input = 5 mVpp | | 6.5 | | | |
| RJ | | Input = 10 mVpp | | 3 | | ps _{RMS} | |
| t _r | Output rise time | 20% to 80% | | 60 | 85 | ps | |
| tf | Output fall time | 20% to 80% | | 60 | 85 | ps | |
| tDIS | Disable response time | | | 20 | | ns | |

NOTE 2: Deterministic jitter does not include pulse-width distortion due to residual small output offset voltage.

APPLICATION INFORMATION

Figure 3 shows the ONET2511PA connected with an ac-coupled interface to the data signal source as well as to the output load.

The ac-coupling capacitors C_1 through C_4 in the input and output data signal lines are the only required external components. In addition, an optional external filter capacitor (C_{OC}) may be used if a low cutoff frequency is desired.

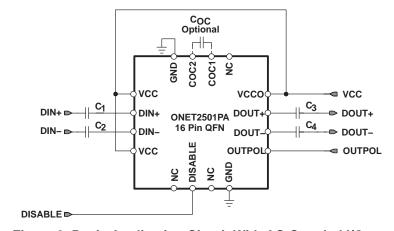


Figure 3. Basic Application Circuit With AC-Coupled I/Os

RGT (S-PQFP-N16) PLASTIC QUAD FLATPACK 3,15 2,85 3,15 2,85 PIN 1 INDEX AREA TOP AND BOTTOM 1,00 0,80 0,20 REF. -SEATING PLANE 0,08 0,05 0,00 1,80 MAX SQ.- $16X \frac{0,50}{0,30}$ 16 13 EXPOSED THERMAL DIE PAD (SEE NOTE D) 12 - $16X \frac{0.30}{0.18} \boxed{\oplus 0.10 \text{ }}$ 0,50 1,50 4203495/D 02/04

- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 - D. The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane.
 - E. Falls within JEDEC MO-220.



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